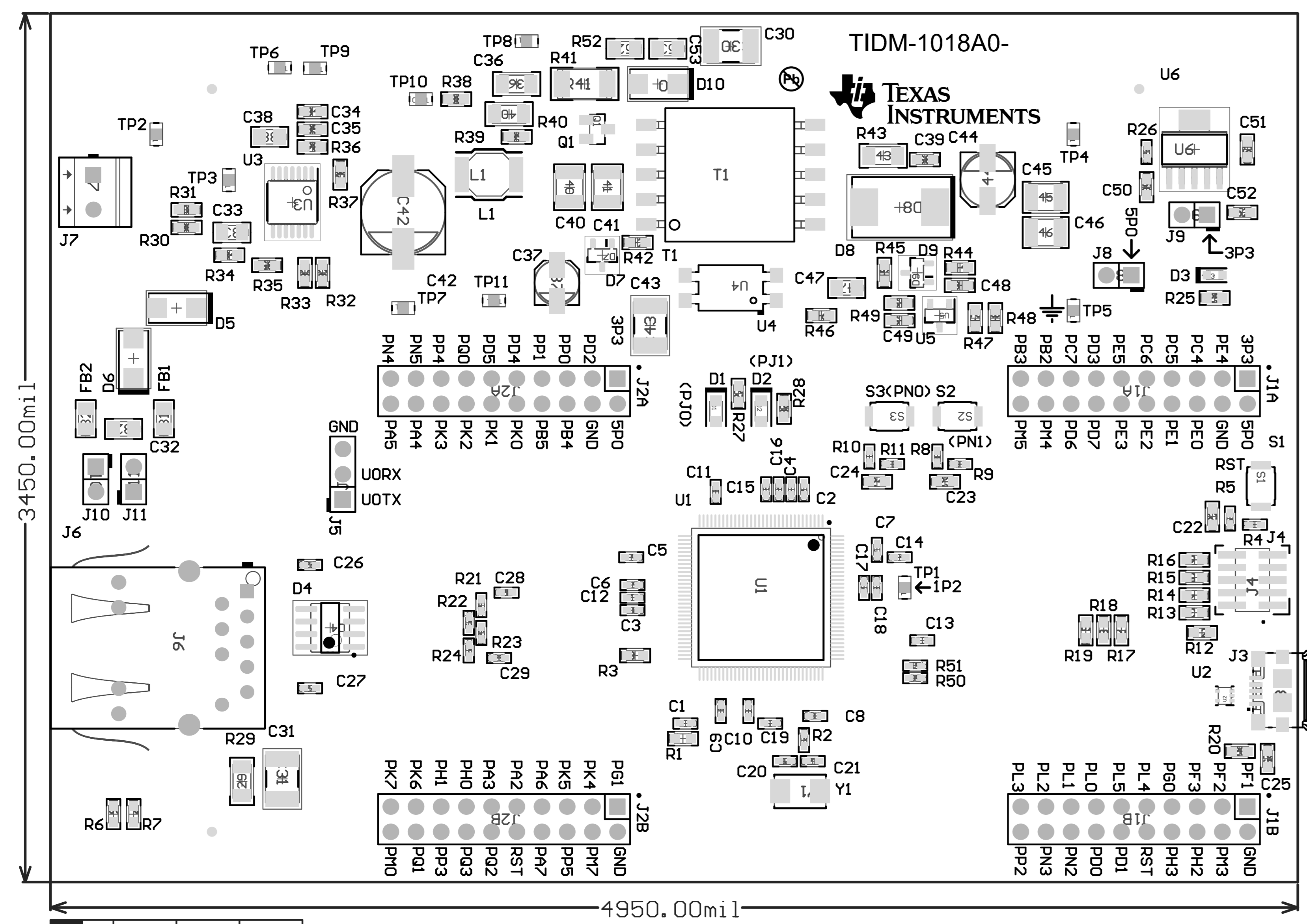


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3

RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

COMPONENTS MARKED 'DNP' SHOULD NOT BE OBTAINED FROM THE SUPPLIER. COMPONENTS MARKED 'DNP' SHOULD NOT BE OBTAINED FROM THE SUPPLIER.

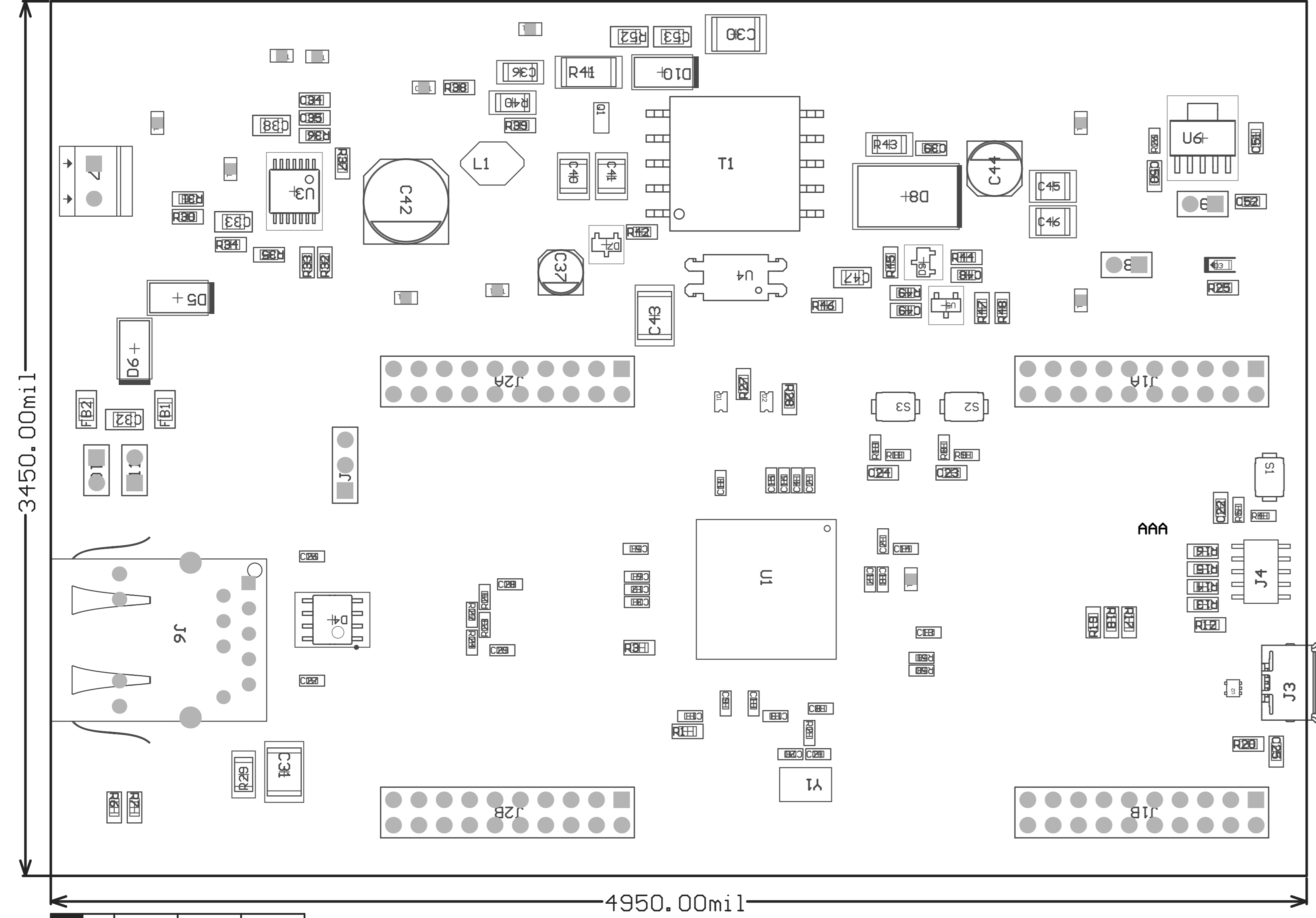
ASSEMBLY VARIANT: [No Variations]

ADDITIONAL COMMENTS	BOARD #:	8100M40018	DATE:	AO	SUN 3008:00:00 08/08/2018
LAYER NAME = Mephonic1112	TID #:	8100M40018	#	DIT	
PLT DATE: 20180808	PLT TIME: 9:48:48 AM	TEXAS INSTRUMENTS			

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ENGINEER:	Amit Ashara	LAYOUT BY:	Amit Ashara
SCALE:	1.00	ALTIUM DESIGNER VERSION:	17.1.5.472

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIC
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED. THIS BOARD IS A PUBLIC RELEASE BOARD. COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED. THIS BOARD IS A PUBLIC RELEASE BOARD.
 ASSEMBLY VARIANT: [No Variations] [no variations] :TIAIRAU YJME22A

ADDITIONAL COMMENTS: BOARD IS A PUBLIC RELEASE BOARD.	OA: BOARD #:	8T0DMM0018	# DIT	DATE: AO	SUN 3008: 10/27/2013 9:48:52 AM	TEXAS INSTRUMENTS
LAYER NAME = Bottom Overlay	TID #:	8T0DMM0018	# DIT			
PLT DATE: 10/27/2013 9:48:52 AM	GENERATED BY:					

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ENGINEER:	AMIT ASHARA	LAYOUT BY:	AMIT ASHARA
SCALE:	1.00	ALTIUM DESIGNER VERSION:	17.1.5.472

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